



PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Confirmation No.: Not Yet Assigned

Group Art Unit: 2814

Filed: March 29, 2000

Examiner: N. Ha

For: CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED WIRING SUBSTRATE, AND CAPACITOR

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the outstanding Office Action of June 7, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 14 and 15.

Please enter the following amended claims:

1. (Amended) A printed wiring substrate having a planar surface and a built-in capacitor on which an IC chip is mounted, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

A.
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